



PATENT
YOR920030206US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

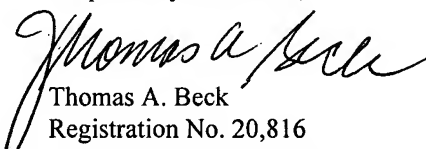
In re Application of : Larry Shungwei Mok
Serial Number : 10/784,624
Filing Date : February 23, 2004
Examiner : Tho V. Duong
Group Art Unit : 3753
For : HEAT DISSIPATION INTERFACE FOR
SEMICONDUCTOR STRUCTURES

TO: The Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

In response to the Official Action dated May 17, 2007, relating to the above-identified application please consider the enclosed amendment which amends the claims to conform to the requirements of 37 C.F.R. 1.121 or 1.4.

Please address all future correspondence in this application to the undersigned as attorney of record at 6136 West Kimberly Way, Glendale, AZ 85308.

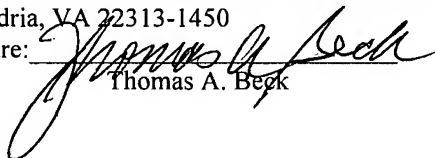
Respectfully Submitted,


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I hereby certify that this paper is being transmitted via the United States Postal Service, in a sealed envelope, postage prepaid, on the date indicated below, addressed to Commissioner of Patents & Trademarks, Post Office Box 1450, Alexandria, VA 22313-1450

Signature:

Name:


Thomas A. Beck

Date: June 14, 2007